

[CHIP PACKAGE STRUCTURE AND METHOD FOR MANUFACTURING THE SAME]

Abstract

The present invention relates to a method for manufacturing a semiconductor chip package structure including the following steps. A substrate is provided. A plurality of chips are assembled onto the substrate and are electrically connected with the substrate. A stiffener is assembled onto the substrate and the stiffener has a top surface and a bottom surface facing the substrate. A molding compound is formed to cover the semiconductor chip, the substrate, the top surface and the bottom surface of the stiffener. Afterwards, a singulation step is performed to cut the molding compound, the substrate and the stiffener.